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July 2015

FDMS86101DC

N-Channel Dual CoolTM 56 Shielded Gate PowerTrench[®] MOSFET 100 V, 60 A, 7.5 m Ω

Features

- Shielded Gate MOSFET Technology
- Dual CoolTM Top Side Cooling PQFN package
- Max $r_{DS(on)} = 7.5 \text{ m}\Omega$ at $V_{GS} = 10 \text{ V}$, $I_D = 14.5 \text{ A}$
- Max $r_{DS(on)} = 12 \text{ m}\Omega$ at $V_{GS} = 6 \text{ V}$, $I_D = 11.5 \text{ A}$
- High performance technology for extremely low r_{DS(on)}
- 100% UIL Tested
- RoHS Compliant

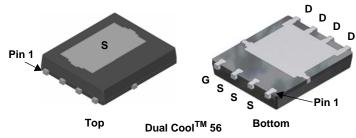


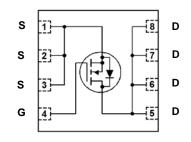
General Description

This N-Channel MOSFET is produced using Fairchild Semiconductor's advanced PowerTrench® process that incorporates Shielded Gate technology. Advancements in both silicon and Dual $\mathsf{Cool}^\mathsf{TM}$ package technologies have been combined to offer the lowest $r_{\mathsf{DS(on)}}$ while maintaining excellent switching performance by extremely low Junction-to-Ambient thermal resistance.

Applications

- Primary DC-DC MOSFET
- Secondary Synchronous Rectifier
- Load Switch





MOSFET Maximum Ratings $T_A = 25$ °C unless otherwise noted

Symbol	Parame	eter		Ratings	Units
V _{DS}	Drain to Source Voltage			100	V
V_{GS}	Gate to Source Voltage			±20	V
	Drain Current -Continuous	T _C = 25 °C		60	
I_D	-Continuous	T _A = 25 °C	(Note 1a)	14.5	Α
	-Pulsed			200	
E _{AS}	Single Pulse Avalanche Energy		(Note 3)	216	mJ
D	Power Dissipation	T _C = 25 °C		125	W
P_{D}	Power Dissipation	T _A = 25 °C	(Note 1a)	3.2	VV
T _J , T _{STG}	Operating and Storage Junction Tempera	ture Range		-55 to +150	°C

Thermal Characteristics

$R_{\theta JC}$	Thermal Resistance, Junction to Case	(Top Source)	2.3	
$R_{\theta JC}$	Thermal Resistance, Junction to Case	(Bottom Drain)	1.0	
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient	(Note 1a)	38	
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient	(Note 1b)	81	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient	(Note 1i)	16	
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient	(Note 1j)	23	
$R_{\theta,JA}$	Thermal Resistance, Junction to Ambient	(Note 1k)	11	

Package Marking and Ordering Information

Device Marking	Device	Package	Reel Size	Tape Width	Quantity
86101	FDMS86101DC	Dual Cool TM 56	13"	12 mm	3000 units

Symbol	Parameter	Test Conditions	Min	Тур	Max	Units
Off Chara	cteristics					
BV _{DSS}	Drain to Source Breakdown Voltage	$I_D = 250 \mu A, V_{GS} = 0 V$	100			V
$\frac{\Delta BV_{DSS}}{\Delta T_{J}}$	Breakdown Voltage Temperature Coefficient	I_D = 250 μ A, referenced to 25°C		70		mV/°C
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} = 80 V, V _{GS} = 0 V			1	μΑ
I _{GSS}	Gate to Source Leakage Current	$V_{GS} = \pm 20 \text{ V}, V_{DS} = 0 \text{ V}$			±100	nA

On Characteristics

$V_{GS(th)}$	Gate to Source Threshold Voltage	$V_{GS} = V_{DS}, I_D = 250 \mu A$	2	2.7	4	V
$\Delta V_{GS(th)} \over \Delta T_J$	Gate to Source Threshold Voltage Temperature Coefficient	$I_D = 250 \mu A$, referenced to 25 °C		-10		mV/°C
		$V_{GS} = 10 \text{ V}, I_D = 14.5 \text{ A}$		6	7.5	
r _{DS(on)}	Static Drain to Source On Resistance	$V_{GS} = 6 \text{ V}, I_D = 11.5 \text{ A}$		8.3	12	mΩ
, ,		$V_{GS} = 10 \text{ V}, I_D = 14.5 \text{ A}, T_J = 125 \text{ °C}$		10	13	
9 _{FS}	Forward Transconductance	$V_{DD} = 10 \text{ V}, I_D = 14.5 \text{ A}$		44		S

Dynamic Characteristics

C _{iss}	Input Capacitance	V 50.V. V 0.V		2354	3135	pF
C _{oss}	Output Capacitance	$V_{DS} = 50 \text{ V}, V_{GS} = 0 \text{ V},$ $f = 1 \text{ MHz}$		467	625	pF
C _{rss}	Reverse Transfer Capacitance	1 - 1 1011 12		23	35	pF
R_{g}	Gate Resistance		0.1	1.4	3	Ω

Switching Characteristics

t _{d(on)}	Turn-On Delay Time			14	25	ns
t _r	Rise Time	V _{DD} = 50 V , I _D = 1		8.2	17	ns
t _{d(off)}	Turn-Off Delay Time	V _{GS} = 10 V, R _{GEN} :	= 6 Ω	25	40	ns
t _f	Fall Time			5.5	11	ns
0	Total Gate Charge	$V_{GS} = 0 V \text{ to } 10 V$		31	44	nC
$Q_{g(TOT)}$	Total Gate Charge	$V_{GS} = 0 V to 5 V$	V _{DD} = 50 V	18	25	nC
Q _{gs}	Total Gate Charge		V _{DD} = 50 V I _D = 14.5 A	8.3		nC
Q_{gd}	Gate to Drain "Miller" Charge			7		nC

Drain-Source Diode Characteristics

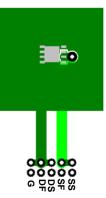
V _{SD} Source to Drain Diode Fore	Source to Drain Diode, Ferward Voltage	$V_{GS} = 0 \text{ V}, I_S = 2.7 \text{ A}$ (Note 2))	0.71	1.2	V	
	Source to Drain blode Polward voltage	$V_{GS} = 0 \text{ V}, I_S = 14.5 \text{ A}$ (Note 2))	0.78	1.3	V	
t _{rr}	Reverse Recovery Time	-I _E = 14.5 A. di/dt = 100 A/μs		54	87	ns	
Q_{rr}	Reverse Recovery Charge	$I_F = 14.5 \text{ A}, \text{ di/dt} = 100 \text{ A/}\mu\text{S}$		62	99	nC	

Thermal Characteristics

$R_{\theta JC}$	Thermal Resistance, Junction to Case	(Top Source)	2.3	
$R_{\theta JC}$	Thermal Resistance, Junction to Case	(Bottom Drain)	1.0	
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient	(Note 1a)	38	
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient	(Note 1b)	81	
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient	(Note 1c)	27	
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient	(Note 1d)	34	
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient	(Note 1e)	16	90044
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient	(Note 1f)	19	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient	(Note 1g)	26	
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient	(Note 1h)	61	
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient	(Note 1i)	16	
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient	(Note 1j)	23	
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient	(Note 1k)	11	
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient	(Note 1I)	13	

NOTES

1. R_{0,1A} is determined with the device mounted on a FR-4 board using a specified pad of 2 oz copper as shown below. R_{0,1C} is guaranteed by design while R_{0,1C} is determined by the user's board design.



a. 38 °C/W when mounted on a 1 in² pad of 2 oz copper



b. 81 °C/W when mounted on a minimum pad of 2 oz copper

- c. Still air, 20.9x10.4x12.7mm Aluminum Heat Sink, 1 in² pad of 2 oz copper
- d. Still air, 20.9x10.4x12.7mm Aluminum Heat Sink, minimum pad of 2 oz copper
- e. Still air, 45.2x41.4x11.7mm Aavid Thermalloy Part # 10-L41B-11 Heat Sink, 1 in² pad of 2 oz copper
- f. Still air, 45.2x41.4x11.7mm Aavid Thermalloy Part # 10-L41B-11 Heat Sink, minimum pad of 2 oz copper
- g. 200FPM Airflow, No Heat Sink,1 in² pad of 2 oz copper
- h. 200FPM Airflow, No Heat Sink, minimum pad of 2 oz copper
- i. 200FPM Airflow, 20.9x10.4x12.7mm Aluminum Heat Sink, 1 \mbox{in}^2 pad of 2 oz copper
- j. 200FPM Airflow, 20.9x10.4x12.7mm Aluminum Heat Sink, minimum pad of 2 oz copper
- k. 200FPM Airflow, 45.2x41.4x11.7mm Aavid Thermalloy Part # 10-L41B-11 Heat Sink, 1 in² pad of 2 oz copper
- I. 200FPM Airflow, 45.2x41.4x11.7mm Aavid Thermalloy Part # 10-L41B-11 Heat Sink, minimum pad of 2 oz copper
- 2. Pulse Test: Pulse Width < 300 $\mu\text{s},$ Duty cycle < 2.0%.
- 3. Starting T $_{J}$ = 25 $^{o}C;$ N-ch: L = 0.3 mH, I $_{AS}$ = 38 A, V $_{DD}$ = 90 V, V $_{GS}$ = 10 V.

Typical Characteristics $T_J = 25$ °C unless otherwise noted

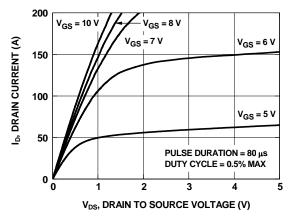


Figure 1. On-Region Characteristics

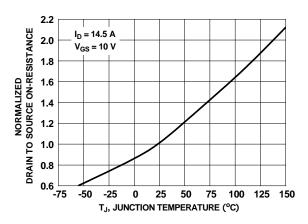


Figure 3. Normalized On-Resistance vs Junction Temperature

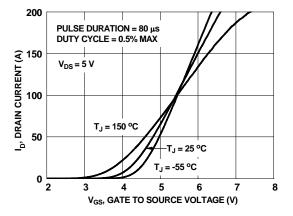


Figure 5. Transfer Characteristics

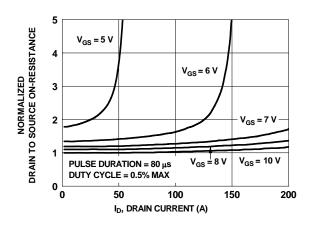


Figure 2. Normalized On-Resistance vs Drain Current and Gate Voltage

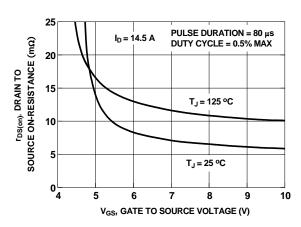


Figure 4. On-Resistance vs Gate to Source Voltage

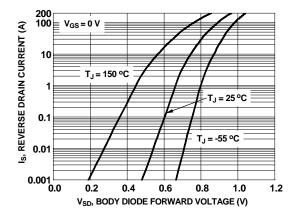


Figure 6. Source to Drain Diode Forward Voltage vs Source Current

Typical Characteristics $T_J = 25$ °C unless otherwise noted

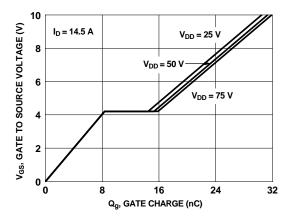


Figure 7. Gate Charge Characteristics

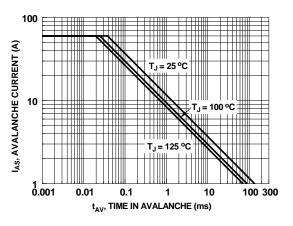


Figure 9. Unclamped Inductive Switching Capability

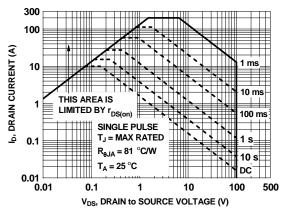


Figure 11. Forward Bias Safe Operating Area

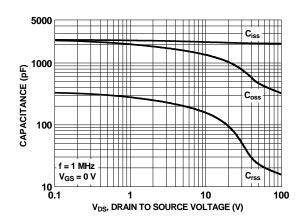


Figure 8. Capacitance vs Drain to Source Voltage

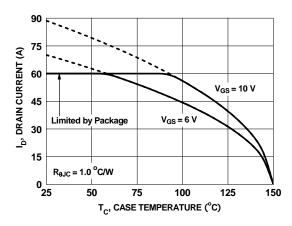


Figure 10. Maximum Continuous Drain Current vs Case Temperature

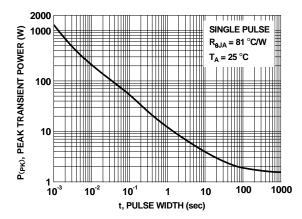


Figure 12. Single Pulse Maximum Power Dissipation



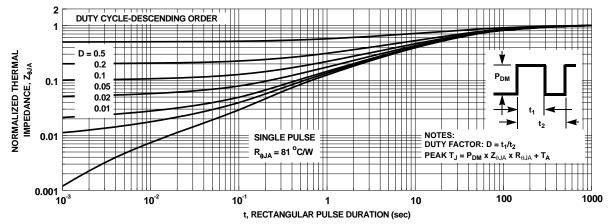
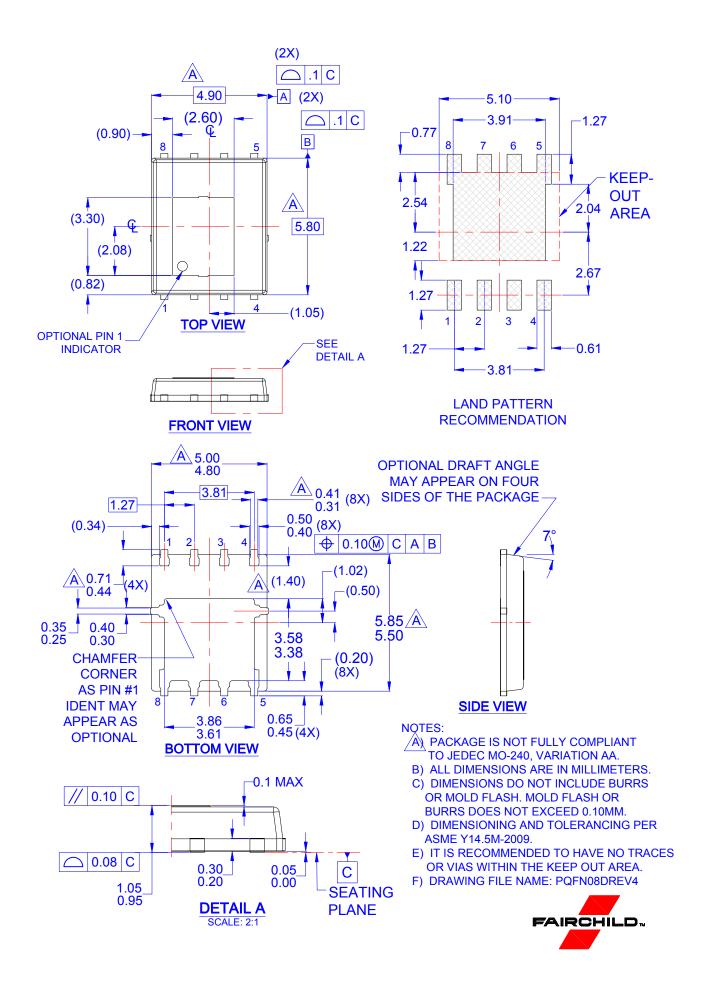


Figure 13. Junction-to-Ambient Transient Thermal Response Curve



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